

Connector for Memory Stick™

SCEC Series



ESD (electro-static discharge) protection model whose robust structure achieves high reliability.

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For W-SIM

For Memory Stick Micro™

For Memory Stick™

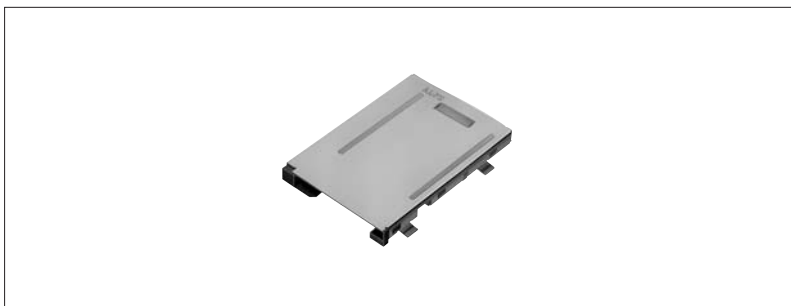
Combine Type

For Compact Flash™

For PC cards supporting CardBus

For Express Card™

For CMOS Camera Module



Features

- Improved operability from long ejection stroke (10mm) and clear click feel.
- 4 solder lug terminals are provided in the plate for secure mounting onto the PC board.
- Allows setting of media locking mechanism.
- Reflow solderable.

Applications

- For compact audio equipment, personal digital assistants, desktop PCs and notebook PCs
- For home audio equipment (TVs, set top boxes and recorders)
- For digital camcorders, digital still cameras, and headphone players

Typical Specifications

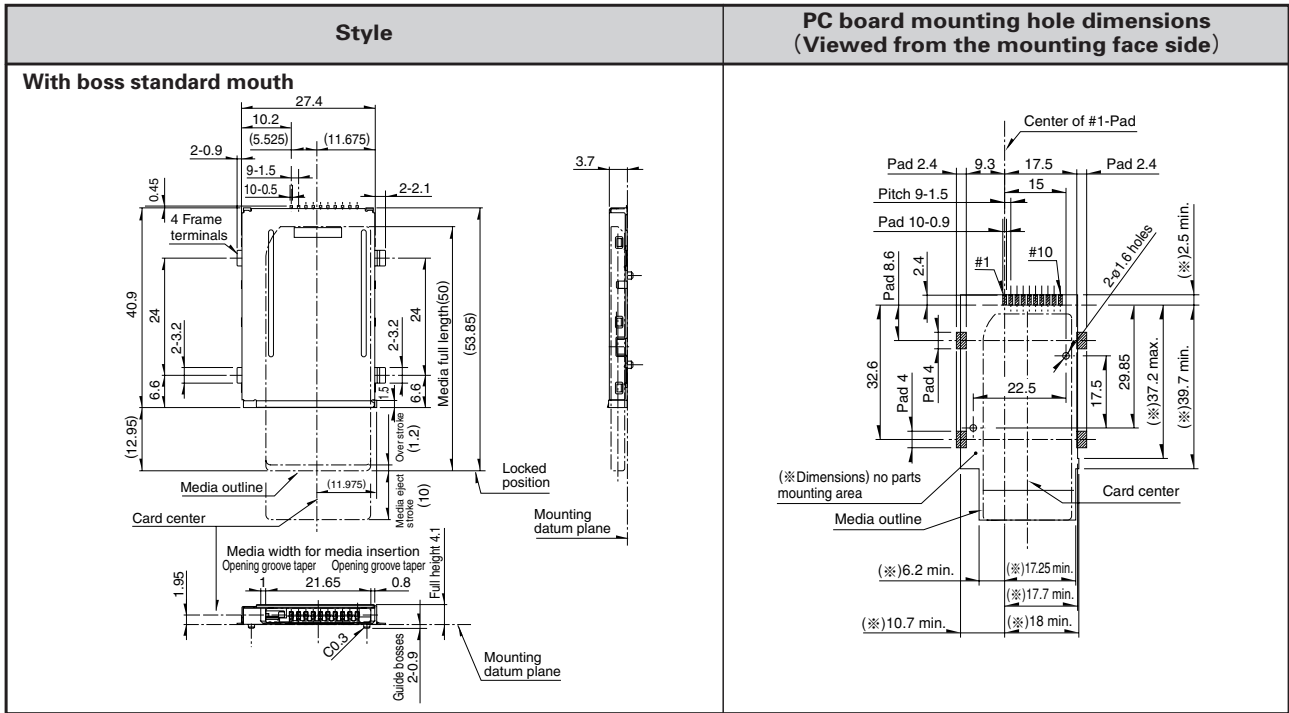
Items		Specifications
Structure	Applicable media	Memory Stick™
	Mounting type	Surface mounting type
	Mounting style	Standard mount
	Media ejection structure	Push-push type
Performance	Operating temperature range	-20°C to +60°C
	Voltage proof	500V AC 1minute
	Insulation resistance (Initial)	1,000MΩ min.
	Contact resistance (Initial)	40mΩ max.
	Insertion and removal cycle	12,000cycles

Product Line

Media ejection structure	Mounting system	Features	Stand-off (mm)	Packing system	Product No.
Push-push type	Standard mount	With boss standard mouth	0	Tray	SCEC1B0100

Dimensions

Unit:mm



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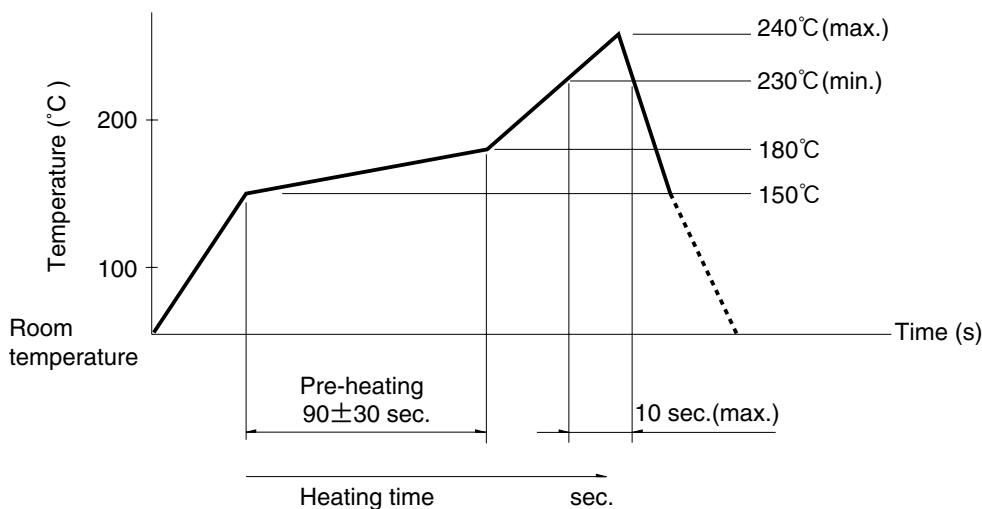
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Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile (Surface of products).



Cautions for using this product

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. Avoid use of water-soluble soldering flux, since it may corrode the product.
3. Check and conform to reflow soldering requirements under actual mass production conditions.
4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
5. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.

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